MOSFETs Silicon N-Channel MOS (DTMOS V)

TK560P60Y

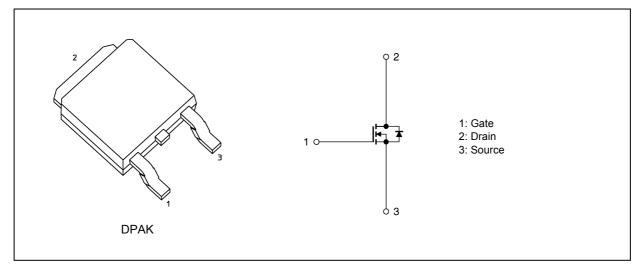
1. Applications

• Switching Voltage Regulators

2. Features

- (1) Low drain-source on-resistance: $R_{DS(ON)} = 0.43 \Omega$ (typ.) by using Super Junction Structure : DTMOS
- (2) Easy to control Gate switching
 - (3) Enhancement mode: V_{th} = 3 to 4 V (V_{DS} = 10 V, I_{D} = 0.24 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25 \ ^{\circ}C$ unless otherwise specified)

| Characteristics | | | | Rating | Unit |
|--------------------------------|---------------------------|----------|------------------|------------|------|
| Drain-source voltage | | | V _{DSS} | 600 | V |
| Gate-source voltage | | | V _{GSS} | ±30 | 7 |
| Drain current (DC) | (T _c = 25 °C) | (Note 1) | Ι _D | 7 | Α |
| Drain current (DC) | (T _c = 100 °C) | (Note 1) | Ι _D | 4.4 | Α |
| Drain current (pulsed) | (T _c = 25 °C) | (Note 1) | I _{DP} | 28 | Α |
| Power dissipation | (T _c = 25 °C) | | PD | 60 | W |
| Single-pulse avalanche energy | | (Note 2) | E _{AS} | 64 | mJ |
| Single-pulse avalanche current | | | I _{AS} | 1.8 | Α |
| Reverse drain current (DC) | | (Note 1) | I _{DR} | 7 | 1 |
| Reverse drain current (pulsed) | | (Note 1) | I _{DRP} | 28 | Α |
| Channel temperature | | | T _{ch} | 150 | °C |
| Storage temperature | | | T _{stg} | -55 to 150 | °C |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production

2016-12

5. Thermal Characteristics

| Characteristics | | Max | Unit |
|---------------------------------------|-----------------------|------|------|
| Channel-to-case thermal resistance | | 2.08 | °C/W |
| Channel-to-ambient thermal resistance | R _{th(ch-a)} | 125 | |

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: V_{DD} = 90 V, T_{ch} = 25 °C (initial), L = 34.8 mH, R_G = 25 Ω , I_{AS} = 1.8 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|--------------------------------|----------------------|--|-----|------|------|------|
| Gate leakage current | I _{GSS} | V_{GS} = ±30 V, V_{DS} = 0 V | _ | _ | ±1 | μA |
| Drain cut-off current | I _{DSS} | V _{DS} = 600 V, V _{GS} = 0 V | _ | _ | 10 | |
| Drain-source breakdown voltage | V _{(BR)DSS} | I _D = 10 mA, V _{GS} = 0 V | 600 | _ | _ | V |
| Gate threshold voltage | V _{th} | V _{DS} = 10 V, I _D = 0.24 mA | 3 | _ | 4 | |
| Drain-source on-resistance | R _{DS(ON)} | V _{GS} = 10 V, I _D = 3.5 A | _ | 0.43 | 0.56 | Ω |

6.2. Dynamic Characteristics (Ta = 25 °C unless otherwise specified)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|--------------------------------|--------------------|---|-----|------|-----|------|
| Input capacitance | C _{iss} | V _{DS} = 300 V, V _{GS} = 0 V, f = 100 kHz | _ | 380 | — | pF |
| Reverse transfer capacitance | C _{rss} | | _ | 2.5 | — | |
| Output capacitance | C _{oss} | | _ | 18 | — | |
| Effective output capacitance | C _{o(er)} | V_{DS} = 0 to 400 V, V_{GS} = 0 V | _ | 30 | _ | |
| Gate resistance | r _g | V _{DS} = OPEN , f = 1 MHz | - | 32 | _ | Ω |
| Switching time (rise time) | tr | See Figure 6.2.1 | | 20 | _ | ns |
| Switching time (turn-on time) | t _{on} | | _ | 50 | _ | |
| Switching time (fall time) | t _f | | _ | 8 | _ | |
| Switching time (turn-off time) | t _{off} | | _ | 105 | _ | |
| MOSFET dv/dt ruggedness | dv/dt | $V_{DS} \le V_{(BR)DSS}, I_D \le 3.5 \text{ A}$ | 50 | _ | _ | V/ns |

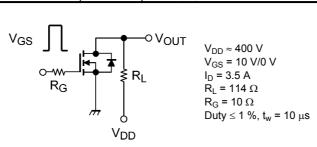


Fig. 6.2.1 Switching Time Test Circuit

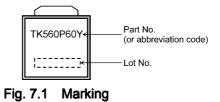
6.3. Gate Charge Characteristics ($T_a = 25$ °C unless otherwise specified)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|--|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | Qg | $V_{DD} \approx 400 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 7 \text{ A}$ | | 14.5 | _ | nC |
| Gate-source charge 1 | Q _{gs1} | | _ | 2.3 | _ | |
| Gate-drain charge | Q _{gd} | | | 7.5 | _ | |

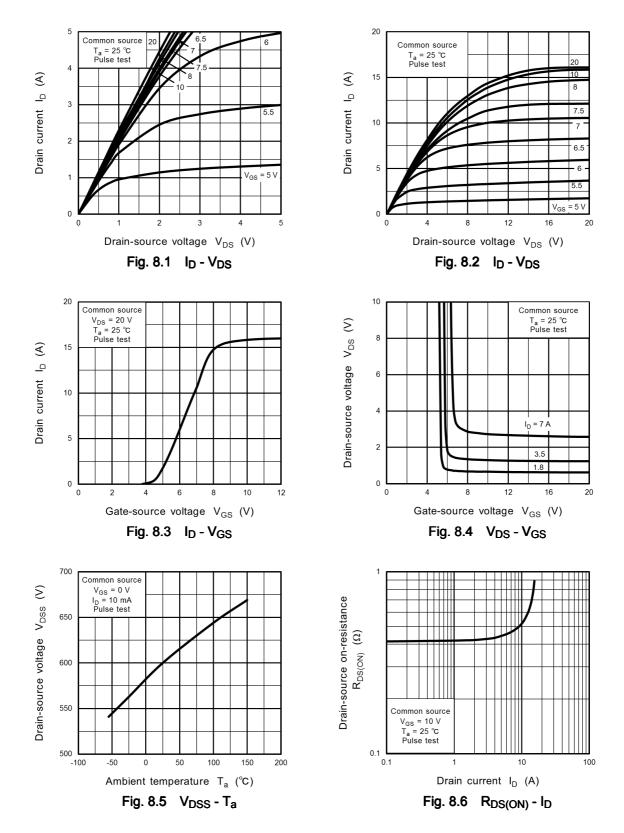
6.4. Source-Drain Characteristics ($T_a = 25$ °C unless otherwise specified)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|-------------------------------|------------------|--|-----|------|------|------|
| Diode forward voltage | V _{DSF} | I _{DR} = 7 A, V _{GS} = 0 V | _ | _ | -1.7 | V |
| Reverse recovery time | t _{rr} | $V_{DD} \approx 400 \text{ V}$ | _ | 240 | _ | ns |
| Reverse recovery charge | Q _{rr} | I _{DR} = 3 A, V _{GS} = 0 V -dI _{DR} /dt = 100 A/μs | | 1.6 | _ | μC |
| Peak reverse recovery current | l _{rr} | | _ | 14.2 | _ | А |
| Diode dv/dt ruggedness | dv/dt | $V_{DS} \leq 400$ V, $I_{DR} \leq 3$ A, V_{GS} = 0 V | 15 | _ | _ | V/ns |

7. Marking



8. Characteristics Curves (Note)



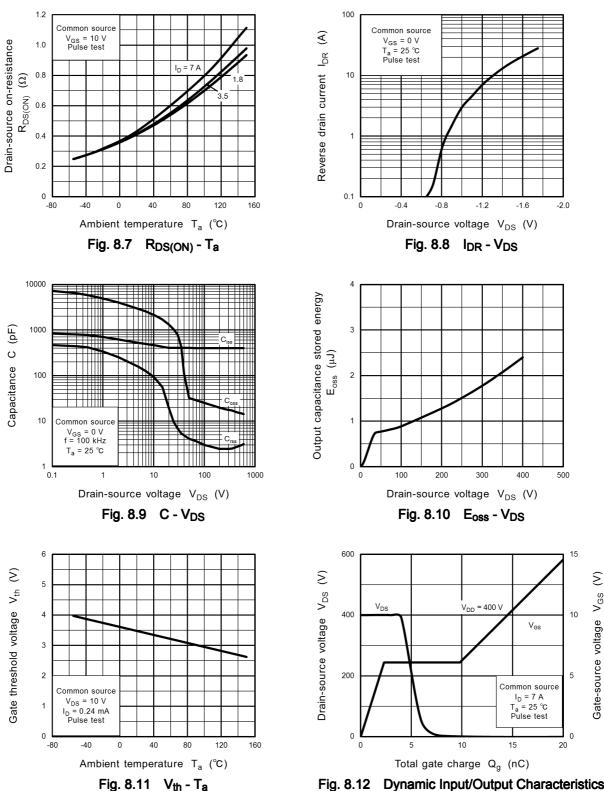


Fig. 8.12 Dynamic Input/Output Characteristics

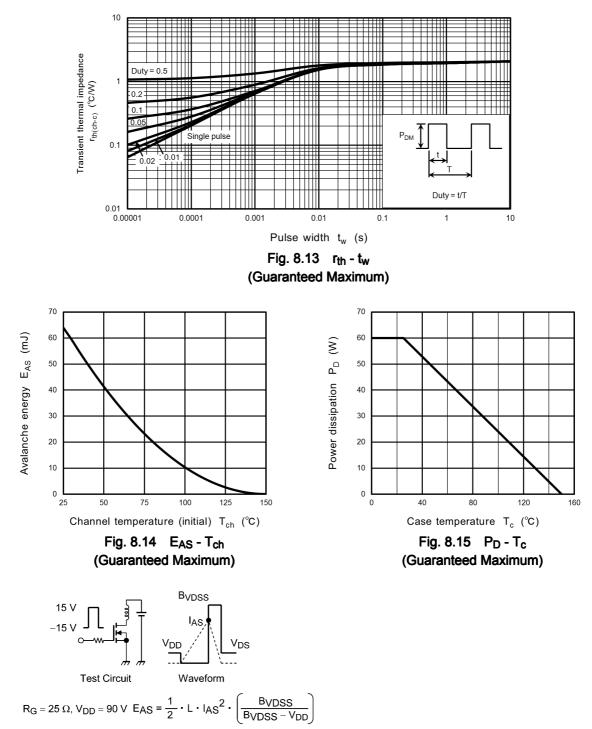
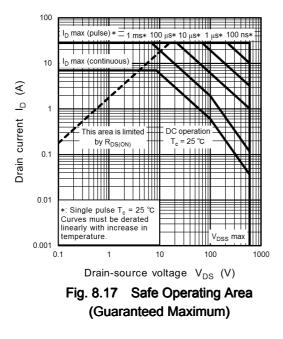


Fig. 8.16 Test Circuit/Waveform



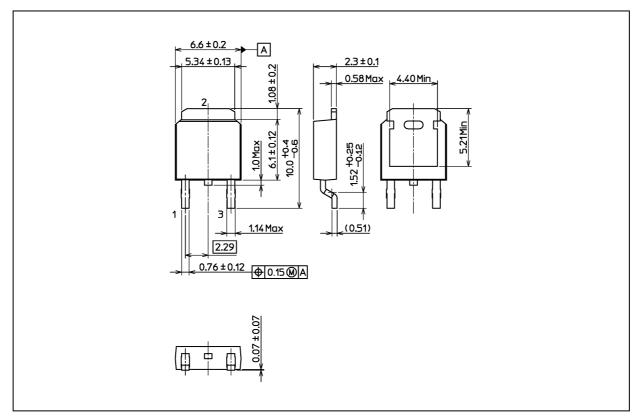
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



TK560P60Y

Package Dimensions

Unit: mm



Weight: 0.36 g (typ.)

| | Package Name(s) | |
|-----------------|-----------------|--|
| TOSHIBA: 2-7K1S | | |
| Nickname: DPAK | | |

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